AUTOMOTIVE GRADE

RoHS COMPLIANT

HALOGEN

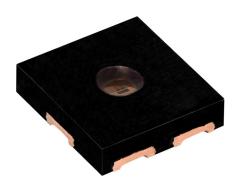
FREE

**GREEN** (5-2008)



## Vishay Semiconductors

# High Accuracy RGBIR Color Sensor With I<sup>2</sup>C Interface



### **LINKS TO ADDITIONAL RESOURCES**





### **DESCRIPTION**

VEML6046X00 is a high accuracy color digital 16-bit resolution sensor in a miniature opaque 2.67 mm x 2.45 mm package. It includes a high sensitive photodiodes, a low noise amplifier, a 16-bit A/D converter and supports an easy to use I2C bus communication interface and additional interrupt feature.

### **FEATURES**

- Package type: surface-mount
- Dimensions (L x W x H in mm): 2.67 x 2.45 x 0.6
- AEC-Q100 qualified
- Integrated modules: RGBIR
- Supply voltage range V<sub>DD</sub>: 2.5 V to 3.6 V
- Communication via I2C interface
- I<sup>2</sup>C bus H-level range: 1.7 V to 3.6 V
- Floor life: 4 weeks, MSL 2a, according to J-STD-020E
- · Low shutdown by current consumption: typ.  $0.5 \mu A$
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



- · RGBIR sensor in automotive for
  - Display backlight controls
  - Infotainment systems
  - Rear view mirror dimming
  - Interior lighting control systems
  - Head-up displays
  - Color recognition
  - CCT measurement
  - Mood lighting

PRODUCT SU	PRODUCT SUMMARY										
PART NUMBER	OPERATING VOLTAGE RANGE (V)	I <sup>2</sup> C BUS VOLTAGE RANGE (V)	PEAK SENSITIVITY (nm)	AMBIENT LIGHT RANGE (lx)	AMBIENT LIGHT RESOLUTION (lx)	OUTPUT CODE	ADC RESOLUTION PROXIMITY / AMBIENT LIGHT				
VEML6046X00	2.5 to 3.6	1.7 to 3.6	600, 550, 470, 820 (R, G, B, IR)	0 to 176 000	0.0053	16 bit, I <sup>2</sup> C	- / 16 bit				

ORDERING IN	ORDERING INFORMATION								
ORDERING CODE	SLAVE ADDRESS (7 BIT)	PACKAGING	VOLUME (1)	REMARKS					
VEML6046X00	0x29	Tape and reel	MOQ: 3000	2.67 mm x 2.45 mm x 0.6 mm					

(1) MOQ: minimum order quantity

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)									
PARAMETER	TEST CONDITION	SYMBOL	MIN.	MAX.	UNIT				
Supply voltage		$V_{DD}$	0	3.6	V				
Ambient temperature range		T <sub>amb</sub>	-40	+110	°C				
Storage temperature range		T <sub>stg</sub>	-40	+110	°C				
Total power dissipation	T <sub>amb</sub> ≤ 25 °C	P <sub>tot</sub>	-	50	mW				
Junction temperature		Tj	-	+110	°C				



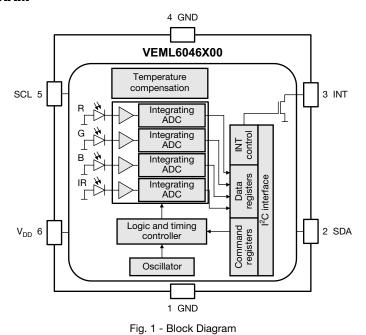
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
ASIC	1201 00112111011	011111202			110011		
Supply voltage		$V_{DD}$	2.5	3.3	3.6	V	
	Shutdown state (1); V <sub>DD</sub> = V <sub>BUS</sub>		-	0.5	-		
Cupply ourrent	Shutdown state <sup>(1)</sup> ; V <sub>DD</sub> = V <sub>BUS</sub> = 3.0 V		-	-	1.2		
Supply current	Shutdown state $^{(1)}$ ; $V_{DD} = 3.6 \text{ V}$ , $V_{BUS} = 1.7 \text{ V}$	I <sub>DD</sub>	-	3.1	-	μA	
	Active state; V <sub>DD</sub> = 3.3 V		-	370	-		
I <sup>2</sup> C clock rate range		f <sub>SCL</sub>	10	_	400	kHz	
I <sup>2</sup> C signal input, logic high	$V_{BUS} = V_{DD}$	M	0.7 x V <sub>BUS</sub>	-	3.6	V	
	V <sub>BUS</sub> ≠ V <sub>DD</sub>	$V_{IH}$	0.85 x V <sub>BUS</sub>	_	-		
I2C signal input logic law	$V_{BUS} = V_{DD}$	V	-0.3	-	0.3 x V <sub>BUS</sub>	V	
I <sup>2</sup> C signal input, logic low	V <sub>BUS</sub> ≠ V <sub>DD</sub>	$V_{IL}$	-0.3	-	0.2 x V <sub>BUS</sub>	V	
Digital current out (low, current sink)		l <sub>ol</sub>	3	-	-	mA	
Digital resolution (LSB count)	With RGB_GAIN = x 2, RGB_IT = 400 ms, RGB_PDDIV = 2/2 PD		-	0.0053	-	lx/coun	
Detectable maximum illuminance	With RGB_GAIN = $\times$ 0.5, RGB_IT = 6.25 ms, RGB_PDDIV = 1/2 PD	E <sub>V max.</sub>	-	176 000	-	lx	
		R	-	2	-		
Dark offset (2)	With RGB_GAIN = x 1, RGB_IT = 400 ms,	G	-	2	-	step	
Daik Oliset V	RGB_PDDIV = 2/2 PD	В	-	2	-	step	
		IR	-	2	-	i l	

#### Notes

 $^{(1)}$  Light conditions:  $E_V = 100 lx$  with 4300K white LED

(2) Light conditions: dark

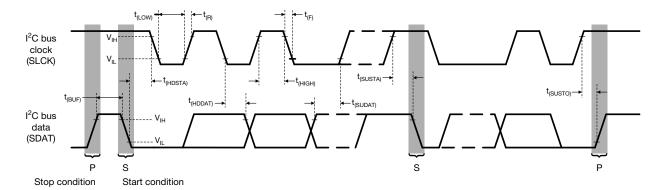
### **CIRCUIT BLOCK DIAGRAM**

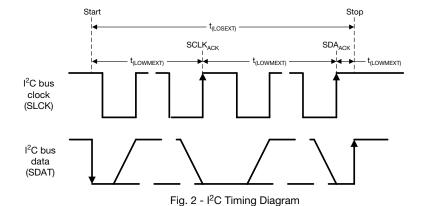


I <sup>2</sup> C TIMING CHARACTERISTICS (T	I <sup>2</sup> C TIMING CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)									
PARAMETER	SYMBOL	STANDAR	D MODE (1)	FAST M	FAST MODE (1)					
PANAIVIETEN	STIVIBOL	MIN.	MAX.	MIN.	MAX.	UNIT				
Clock frequency	f <sub>(SMBCLK)</sub>	10	100	10	400	kHz				
Bus free time between start and stop condition	t <sub>(BUF)</sub>	4.7	-	1.3	-	μs				
Hold time after (repeated) start condition; after this period, the first clock is generated	t <sub>(HDSTA)</sub>	4.0	-	0.6	-	μs				
Repeated start condition setup time	t <sub>(SUSTA)</sub>	4.7	-	0.6	-	μs				
Stop condition setup time	t <sub>(SUSTO)</sub>	4.0	-	0.6	-	μs				
Data hold time	t <sub>(HDDAT)</sub>	0	3450	0	900	ns				
Data setup time	t <sub>(SUDAT)</sub>	250	-	100	-	ns				
I <sup>2</sup> C clock (SCK) low period	t <sub>(LOW)</sub>	4.7	-	1.3	-	μs				
I <sup>2</sup> C clock (SCK) high period	t <sub>(HIGH)</sub>	4.0	-	0.6	-	μs				
Detect clock / data low timeout	t <sub>(TIMEOUT)</sub>	25	35	-	-	ms				
Clock / data fall time	t <sub>(F)</sub>	-	300	-	300	ns				
Clock / data rise time	t <sub>(R)</sub>	-	1000	-	300	ns				

### Note

(1) Data based on standard I<sup>2</sup>C protocol requirement, not tested in production





### PARAMETER TIMING INFORMATION

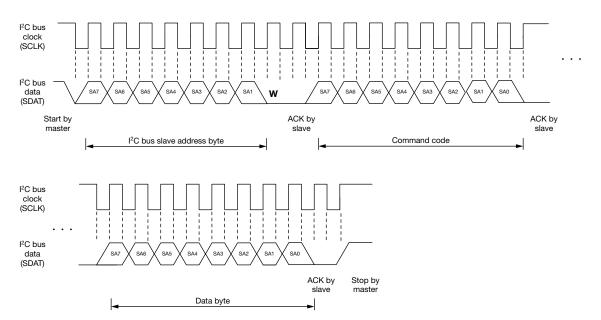


Fig. 3 - I<sup>2</sup>C Bus Timing for Sending Word Command Format

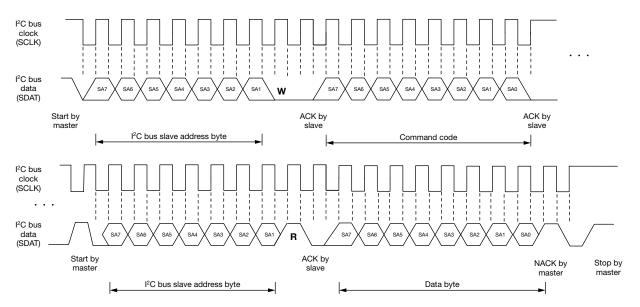


Fig. 4 - I<sup>2</sup>C Bus Timing for Receive Word Command Format

### **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

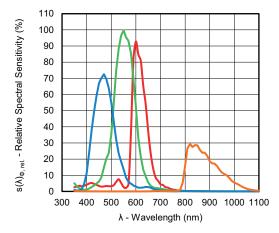


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

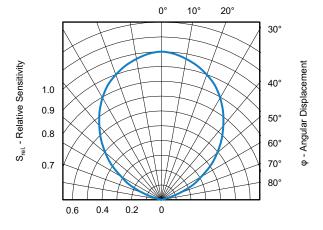


Fig. 6 - Relative Sensitivity vs. Angular Displacement

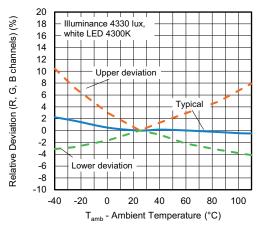


Fig. 7 - Relative Deviation (R, G, B Channels) vs. Temperature (at illumination levels lower than ~200 lux, dark current effects should be taken into account)

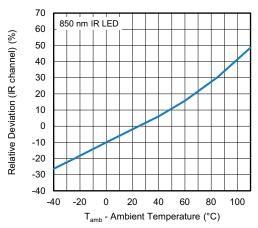


Fig. 8 - Relative Deviation (IR Channel) vs. Ambient Temperature

### **APPLICATION INFORMATION**

### 1. Application Circuit

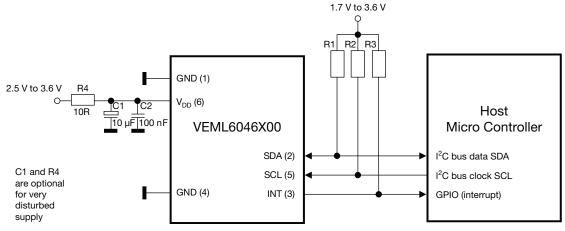


Fig. 9 - Application Circuit (x) = Pin Number

#### **Notes**

- The interrupt pin is an open drain output. Proposed values for the pull-up resistors should be > 1 k $\Omega$ , e.g. 2.2 k $\Omega$  to 4.7 k $\Omega$  for the R1 and R2 (at SDA and SCL) and 10 k $\Omega$  to 100 k $\Omega$  for R3 (at interrupt).
- Normally just one decoupling capacitor is needed. This should be ≥ 100 nF and placed close to the V<sub>DD</sub> pin.
   For detailed description about set-up and use of the interrupt as well as more application related information see AN: "Designing VEML6046X00 into an Application"



### 2. I2C Write and Read Protocol

The VEML6046X00 has 17 register addresses responsible for operation control, parameter setup and result buffering. All registers are accessible via I<sup>2</sup>C communication. Fig. 10 shows the basic I<sup>2</sup>C communication with VEML6046X00.

The built in I<sup>2</sup>C interface is compatible with I<sup>2</sup>C modes "standard" and "fast": 10 kHz to 400 kHz.

Please refer to the I<sup>2</sup>C specification from NXP for details.

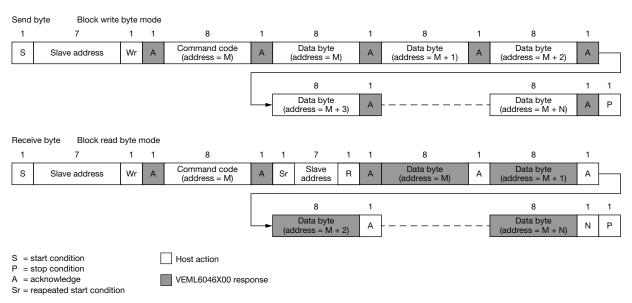


Fig. 10 - Send Byte / Receive Byte Protocol

#### REGISTER INFORMATION

### **Device Address**

The VEML6046X00 is available in one preconfigured slave address. The predefined 7 bit  $I^2C$  bus address is set to 0101001 = 0x29. The least significant bit (LSB) defines read or write mode. Accordingly the bus address is set to 0101 0010 = 0x52 for write and 0101 0011 = 0x53 for read.

TABLE 1 - SLAVE ADDRESS TABLE							
7 BIT SLAVE ADDRESS	8 BIT SLAVE ADDRESS						
0x29	0x52 (Write)	0x53 (Read)					

### **Register Addresses**

The VEML6046X00 has 17 registers, accessible through there respective 8-bit command codes.

Note that due to the location of the two shutdown bits (RGB\_ON\_0 and RGB\_ON\_1), one in register 0x00 and the other in 0x01, it is necessary to always write to both registers at once when configuring the device.

#### **Auto-Memorization**

The VEML6046X00 stores the last measured RGB and IR data before the device is shutdown, keeping the data accessible.

When VEML6046X00 is in shutdown mode, the host can freely read this data via read command directly.

When VEML6046X00 wakes up, the data will be refreshed once a new measurement is made.



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TABLE 2	- COMMAN	D CODE AND RE	GISTER	DESCRIPTION	
COMMAND CODE	DATA BYTE LOW / HIGH	REGISTER NAME	DEFAULT VALUE	FUNCTION	ACCESS
				Set the integration time	
0x00		RGB CONF 0	0x01	Measurement mode of the sensor	
0000	-	NGB_CONF_U	UXU1	Enable interupt function of the green channel	
				Switch the sensor on / off	
				Switch the sensor on / off	Write
0x01	-	RGB_CONF_1	0x80	GAIN and photodiode size setting	and
				Interrupt persistance counter	read
0x04	Low	G_THDH_L	0x00	Green channel high threshold window setting (low byte)	
0x05	High	G_THDH_H	0x00 Green channel high threshold window setting (high		
0x06	Low	G_THDL_L	0x00	Green channel low threshold window setting (low byte)	]
0x07	High	G_THDL_H	0x00	Green channel low threshold window setting (high byte)	
0x10	Low	R_DATA_L	0x00	Low byte of 16-bit red channel result data	
0x11	High	R_DATA_H	0x00	High byte of 16-bit red channel result data	
0x12	Low	G_DATA_L	0x00	Low byte of 16-bit green channel result data	
0x13	High	G_DATA_H	0x00	High byte of 16-bit green channel result data	
0x14	Low	B_DATA_L	0x00	Low byte of 16-bit blue channel result data	
0x15	High	B_DATA_H	0x00	High byte of 16-bit blue channel result data	Read
0x16	Low	IR_DATA_L	0x00	Low byte of 16-bit IR channel result data	only
0x17	High	IR_DATA_H	0x00	High byte of 16-bit IR channel result data	
0x18	Low	VEML6046X00_ID_L	0x01	ID code	
0x19	High	VEML6046X00_ID_H	0x00	ID code	
0x1A	Low	INT_FLAG	0x00	Reserved	
0x1B	High	INT_FLAG	0x00	Interrupt and active force mode event flag	

### Notes

- Command code 0x00 default value is 0x01 = device is shutdown
- · Command 0x00 and command 0x01 must be executed together, they cannot be executed independently

TABLE 3 -	REGISTER	NAME: RGB_C	ONF_0					
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Reserved		RGB_IT		RGB_MODE	RGB_TRIG	G_INT	RGB_ON_0	
		COMMAND COD	E			0x00		
BIT N	IAME	FUNC	TION	BIT	VALUE	DESCR	IPTION	
Rese	erved	Rese	erved	7	0x0 (0b0)	Should be l	kept default	
					0x7 (0b111)	400	ms	
					0x6 (0b110)	200	ms	
					0x5 (0b101)	101) 100 ms		
DO	o IT	Cat the inte	avation time	6 : 4 Ox4 (0b100) 50 ms		ms		
RGI	3_IT	Set the inte	gration time	0:4	0x3 (0b011)	25	25 ms 12.5 ms 6.25 ms	
					0x2 (0b010)	12.5		
					0x1 (0b001)	100 ms 50 ms 25 ms 12.5 ms 6.25 ms 3.125 ms (default) Active force mode Auto mode (default)		
					0x0 (0b000)	3.125 ms	(default)	
DOD	MODE	Set the measu	rement mode	3	0x1 (0b1)	Active fo	rce mode	
RGB_	MODE	of the	sensor	3	0x0 (0b0)	Auto mod	e (default)	
			rce mode trigger;		0x1 (0b1)	Triç	ger	
RGB_	_TRIG		reset to 0 after ement cycle	2	0x0 (0b0)	Off (default)		
	INT	Enable / disab	le the interrupt	1	0x1 (0b1)	Ena	able	
G_	IIN I	function of the	green channel	<u>'</u>	0x0 (0b0)	Disable	(default)	
RGB_	ON_0	and RGB_ON_1 r	Switch the sensor on / off (RGB_ON_0 and RGB_ON_1 must be executed		0x1 (0b1)	0x1 (0b1) Turn off the sensor (default)		
		together to sta	art the sensor)		0x0 (0b0)	Turn on t	he sensor	

### Note

• Command code 0x00 default value is 0x01 = device is shutdown



TABLE 4 -	REGISTER	NAME: RGB_C	ONF_1					
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
RGB_ON_1	RGB_PDDIV	Reserved	RGB_G	iAIN	G_F	PERS	RGB_CAL	
		COMMAND COD	E			0x01		
BIT N	BIT NAME FUNCTION				VALUE	DESCF	IPTION	
		Switch the sensor of	on / off (RGB_ON_0		0x1 (0b1)	Turn on t	he sensor	
RGB_	_ON_1	and RGB_ON_1 r together to sta	nust be executed art the sensor)	7	0x0 (0b0)	Turn off the sensor (shutdown) (default)		
DOD	DDDIV/	Set the effective	photodiode size	6	0x1 (0b1)	1/2 PI	1/2 PD used	
HGB_	PDDIV	for the R,G,B a	and IR channel	б	0x1 (0b1)         1/2 PD used           0x0 (0b0)         2/2 PD used           0x0 (0b0)         Should be kept default           0x3 (0b11)         Gain x0.5			
Rese	erved	Rese	erved	5	0x0 (0b0)	Should be	kept default	
				0x3 (0b11)		Gain	x0.5	
DCD.	CAIN	Sat the gain	of the DCD	4:3	0x2 (0b10)	Gain x0.5 Gain x0.66		
NGD_	_GAIN	Set the gain	of the hab	4.3	0x1 (0b01)	Gai	n x2	
					0x0 (0b00)	Should be kept default Gain x0.5		
					0x3 (0b11)	8 tii	mes	
C B	PERS	Set the amount threshold crossing		2:1	0x2 (0b10)	4 tii	mes	
G_F	Eno	to trigger		2.1	0x1 (0b01)	2 tii	nes	
			•		0x0 (0b00)	1 time	default)	
RGB	RGB CAL		Enable / disable internal calibration after power on		0x1 (0b1)	0x1 (0b1) Enable (must be set to when power on read		
		arter po	WEI OII		0x0 (0b0)	Disable	(default)	

TABLE 5 - REGISTER NAME: G_THDH										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
G_THDH_L										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
			G_TH	DH_H						
COMMAND	BIT NAME	FUNC	TION	BIT	VALUE	DESCR	IPTION			
0x04	G_THDH_L	Set the high threshold interrupt		7:0	0 to 65 535	Low byte				
0x05	G_THDH_H	value of the g	reen channel	7:0	7:0		High byte			

TABLE 6 -	TABLE 6 - REGISTER NAME: G_THDL									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
G_THDL_L										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
			G_TH	DL_H						
COMMAND	BIT NAME	FUNC	TION	BIT	VALUE	DESCR	IPTION			
0x06	G_THDL_L	Set th	Set the low		0 to 65 535	Low byte				
0x07	G_THDL_H	threshold in	terrupt value	7:0	0 10 05 555	High byte				

TABLE 7 -	TABLE 7 - REGISTER NAME: R_DATA									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
	R_DATA_L									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
			R_DA	TA_H						
COMMAND	BIT NAME	FUNC	TION	BIT	VALUE	DESCR	IPTION			
0x10	R_DATA_L	Read the re	Read the red channel		0 to 65 535	Low byte				
0x11	R_DATA_H	outpu	t data	7:0	0 10 00 000	High byte				



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TABLE 8 -	REGISTER N	AME: G_DA1	ΓΑ								
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
G_DATA_L											
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	G_DATA_H										
COMMAND BIT NAME FUNCTION				BIT	VALUE	DESCR	RIPTION				
0x12	G_DATA_L	Read the green channel output data		7:0	0 to 65 535	Low byte					
0x13	G_DATA_H			7:0	0 10 00 000	High byte					

TABLE 9 -	REGISTER N	AME: B_DAT	ΈΑ								
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
B_DATA_L											
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	B_DATA_H										
COMMAND	COMMAND BIT NAME FUNCTION BIT VALUE DESCRIPTION										
0x14	B_DATA_L	Read the b	lue channel	7:0	0 to 65 535	Low	byte				
0x15	B_DATA_H	output data		7:0	0 10 05 555	High byte					

TABLE 10	- REGISTER	NAME: IR_D	ATA								
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
IR_DATA_L											
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	IR_DATA_H										
COMMAND	COMMAND BIT NAME FUNCTION BIT VALUE DESCRIPTION										
0x16	IR_DATA_L	Read the IR channel 7:0 output data 7:0		0 to 65 535	Low byte						
0x17	IR_DATA_H			7:0	0 10 05 555	High byte					

TABLE 11	- REGISTER	NAME: VEM	L6046X00_II	D						
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
VEML6046X00_ID_L										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
	VEML6046X00_ID_H									
COMMAND	BIT N	IAME	FUNCTION	BIT	VALUE	DESCF	RIPTION			
0x18	VEML6046X00_ID_L  VEML6046X00_ID_H		Read the device ID	7:0	0x01 (0b00000001)	Should be	kept default			
0x19				7:0	0x00 (0b00000000)		e with a ess of 0x29			



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TABLE 12	- REGISTER N	NAME: INT_F	LAG				
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
			Rese	rved			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	Reser	rved		AF_DATA_READY	G_IF_L	G_IF_H	Reserved
COMMAND	BIT NAME	FUNC	TION	BIT	VALUE	DESCR	RIPTION
0x1A	Reserved	Rese	erved	7:0	0x00 (0b00000000)	Should be l	kept default
	Reserved	Reserved		7:4	0x0 (0b0000)	Should be kept default	
	AF_DATA_READY	Data ready flag active force mode		3	0x1 (0b1)	Data ready flag available	
	AF_DATA_NEADT			3	0x0 (0b0)	Data ready flag not available	
0x1B	G_IF_L	Low threshold interupt flag		2	0x1 (0b1)	Low threshold crossing interrupt event flag for the green channel	
UX IB					0x0 (0b0)	No low threshold crossing	
	G_IF_H	High threshold interupt flag		1	0x1 (0b1)	High threshold crossing interrupt event flag for the green channel	
					0x0 (0b0)	No high threshold crossing	
	Reserved	Rese	erved	0	0x0 (0b0)	Should be	kept default

### **CALCULATING THE LUX LEVEL**

Command code 0x12 and 0x13 contain the results of the green channel measurement. The value of the green channel can be used to calculated the corresponding illumination. Therefor, the 16-bit code needs to be converted to a decimal value to determine the corresponding lux value. The calculation of the corresponding lux level is dependent on the programmed gain setting and the chosen integration time.

TABLE '	13 - RESC	DLUTION	AND MAX	IMUM DE	TECT	ION RANGE	AT RGB_PI	DDIV (2/2 P	D USED)		
TYPICAL RESOLUTION (lx/cnt)						MAXIMUM POSSIBLE ILLUMINATION (Ix)					
RGB_GAIN							RGB	GAIN			
IT (ms)	x2	x1	x0.66	x0.5		x2	x1	x0.66	x0.5		
400	0.0053	0.0105	0.0159	0.0210		344	688	1043	1376		
200	0.0105	0.0210	0.0318	0.0420		688	1376	2085	2752		
100	0.0210	0.0420	0.0636	0.0840		1376	2752	4170	5505		
50	0.0420	0.0840	0.1273	0.1680		2752	5505	8341	11 010		
25	0.0840	0.1680	0.2545	0.3360		5505	11 010	16 682	22 020		
12.5	0.1680	0.3360	0.5091	0.6720		11 010	22 020	33 363	44 040		
6.25	0.3360	0.6720	1.0182	1.3440		22 020	44 040	66 727	88 079		
3.125	0.6720	1.3440	2.0364	2.6880		(-) <sup>(1)</sup>	(-) <sup>(1)</sup>	(-) <sup>(1)</sup>	(-) <sup>(1)</sup>		

TYPICAL RESOLUTION (lx/cnt)						MAXIMUM POSSIBLE ILLUMINATION (Ix)				
RGB_GAIN							RGB	GAIN		
IT (ms)	x2	x1	x0.66	x0.5	Ī	x2	x1	x0.66	x0.5	
400	0.0105	0.0210	0.0318	0.0420	Ī	688	1376	2085	2752	
200	0.0210	0.0420	0.0636	0.0840		1376	2752	4170	5505	
100	0.0420	0.0840	0.1273	0.1680	Ī	2752	5505	8341	11 010	
50	0.0840	0.1680	0.2545	0.3360		5505	11 010	16 682	22 020	
25	0.1680	0.3360	0.5091	0.6720		11 010	22 020	33 363	44 040	
12.5	0.3360	0.6720	1.0182	1.3440	Ī	22 020	44 040	66 727	88 079	
6.25	0.6720	1.3440	2.0364	2.6880	Ī	44 040	88 079	133 453	176 158	
3.125	1.3440	2.6880	4.0727	5.3760		(-) <sup>(1)</sup>	(-) <sup>(1)</sup>	(-) <sup>(1)</sup>	(-) <sup>(1)</sup>	

### Note

<sup>(1)</sup> For integration time of 3.125 ms the maximum count level is no longer 16 bit, so, half the integration time no longer leads to double the max. lux level



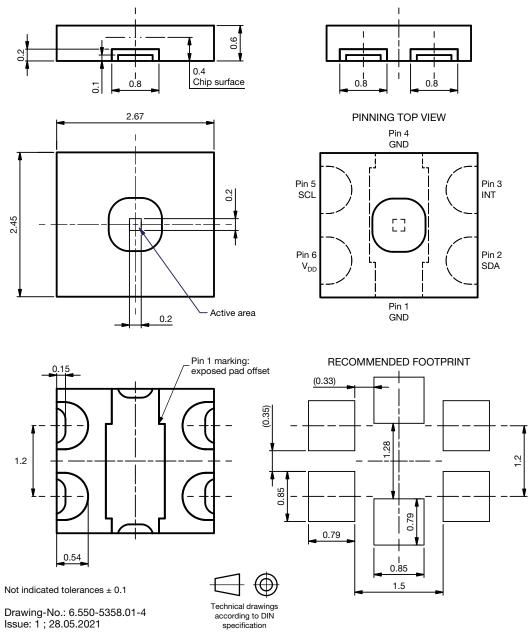
### HANDLING INSTRUCTION

Special care must be taken into consideration when handling the VEML6046X00. VEML6046X00 is sensitive to dust and scratches, proper optical device handling procedures are recommended.

The optical surface of the device must be kept clean for optimal performance in both prototyping with the device and mass production manufacturing procedures. Tweezers with plastic or rubber contact surfaces are recommended to avoid scratches on the optical surface. Avoid manipulation with metal tools when possible. The optical surface must be kept clean of fingerprints, dust, and other optical-inhibiting contaminants. If the device optical surface requires cleaning, the use of isopropyl alcohol is recommended. A few gentle brushes with a soft swab are appropriate. Avoid potentially abrasive cleaning and manipulating tools and excessive force that can scratch the optical surface.

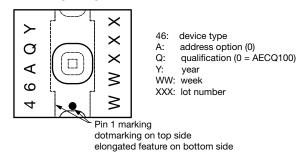
If the VEML6046X00 performs less than optimally, inspect the optical surface for dirt, scratches, or other optical artifacts. VEML6046X00 is a cost effective solution of RGB sensor with I2C bus interface. The standard serial digital interface is easy to access RGB and IR data without complex calculation and programming by external controller. Beside the digital output also a flexible programmable interrupt pin is available.

### **PACKAGE DIMENSIONS** in millimeters

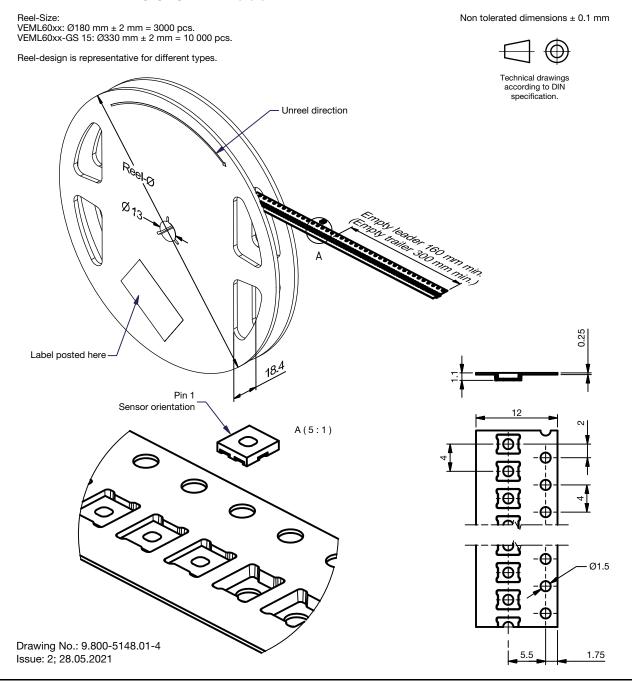




### **MARKING AND PIN 1 IDENTIFICATION**



### **TAPE AND REEL DIMENSIONS** in millimeters



## Vishay Semiconductors

### **DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

### **FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020E.

### **DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020E or label. Devices taped on reel dry using recommended conditions 192 h at 40  $^{\circ}$ C (+ 5  $^{\circ}$ C), RH < 5  $^{\circ}$ M.

### **REFLOW SOLDER PROFILE**

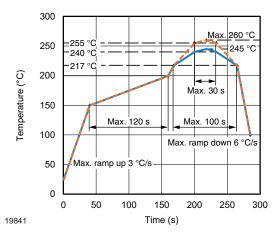


Fig. 11 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020E

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